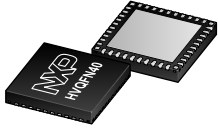


SOT618-20(D)

HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals,
0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

23 October 2025

Package information



1 Package summary

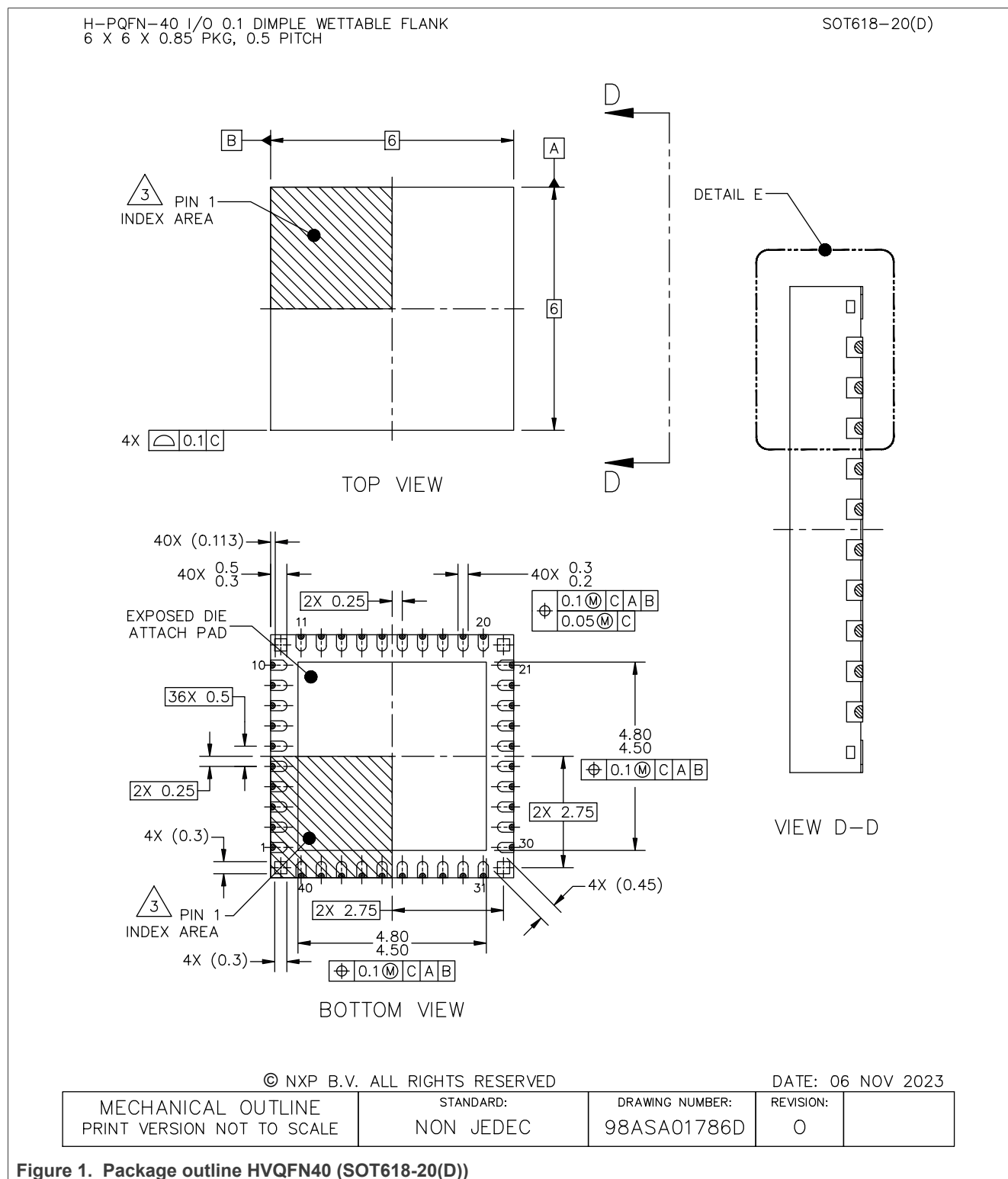
Terminal position code	Q (quad)
Package type descriptive code	HVQFN40
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	06-11-2023
Manufacturer package code	98ASA01786D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	5.9	6	6.1	mm
package width	5.9	6	6.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	40	-	

HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

2 Package outline



HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

3 Soldering

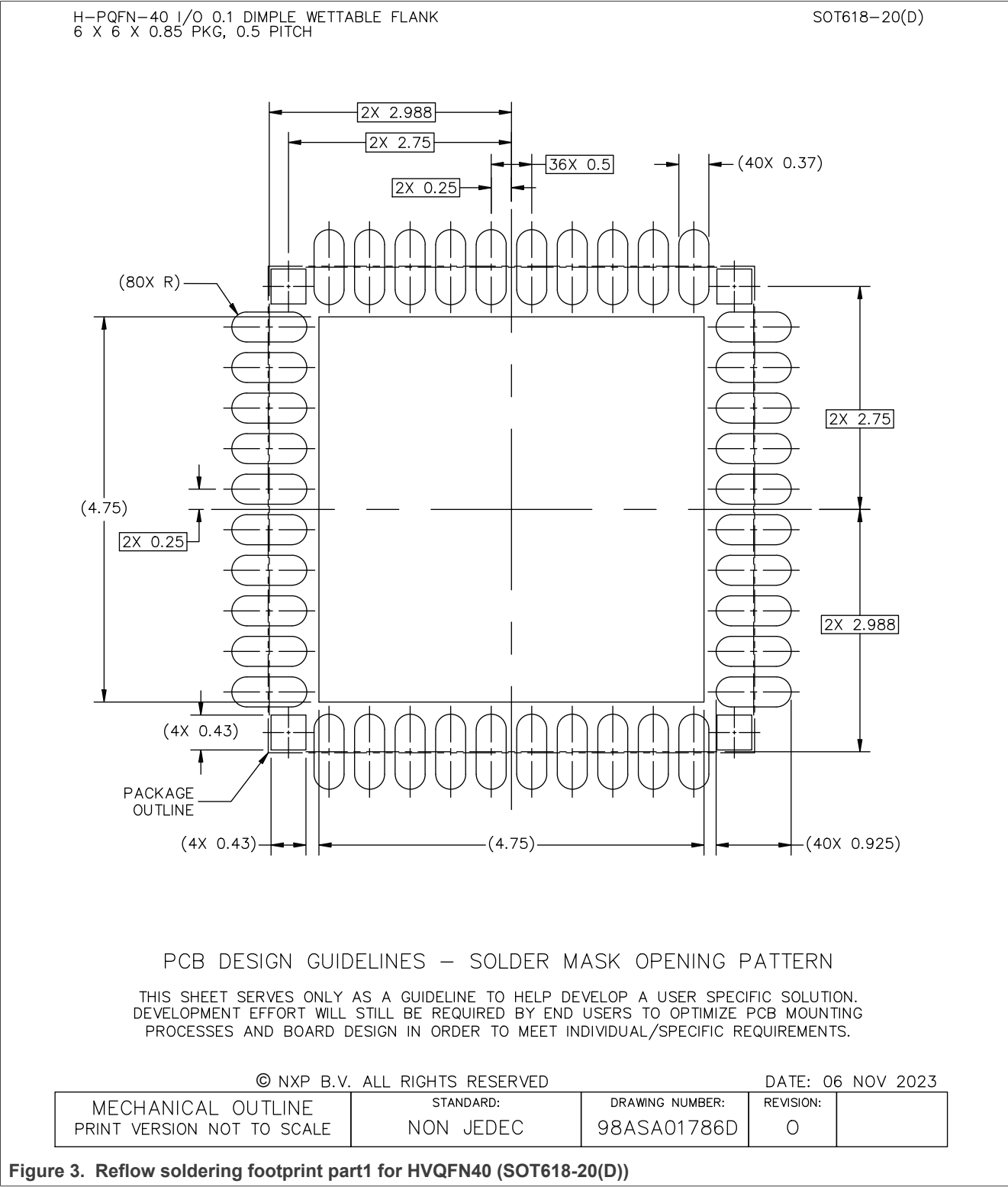
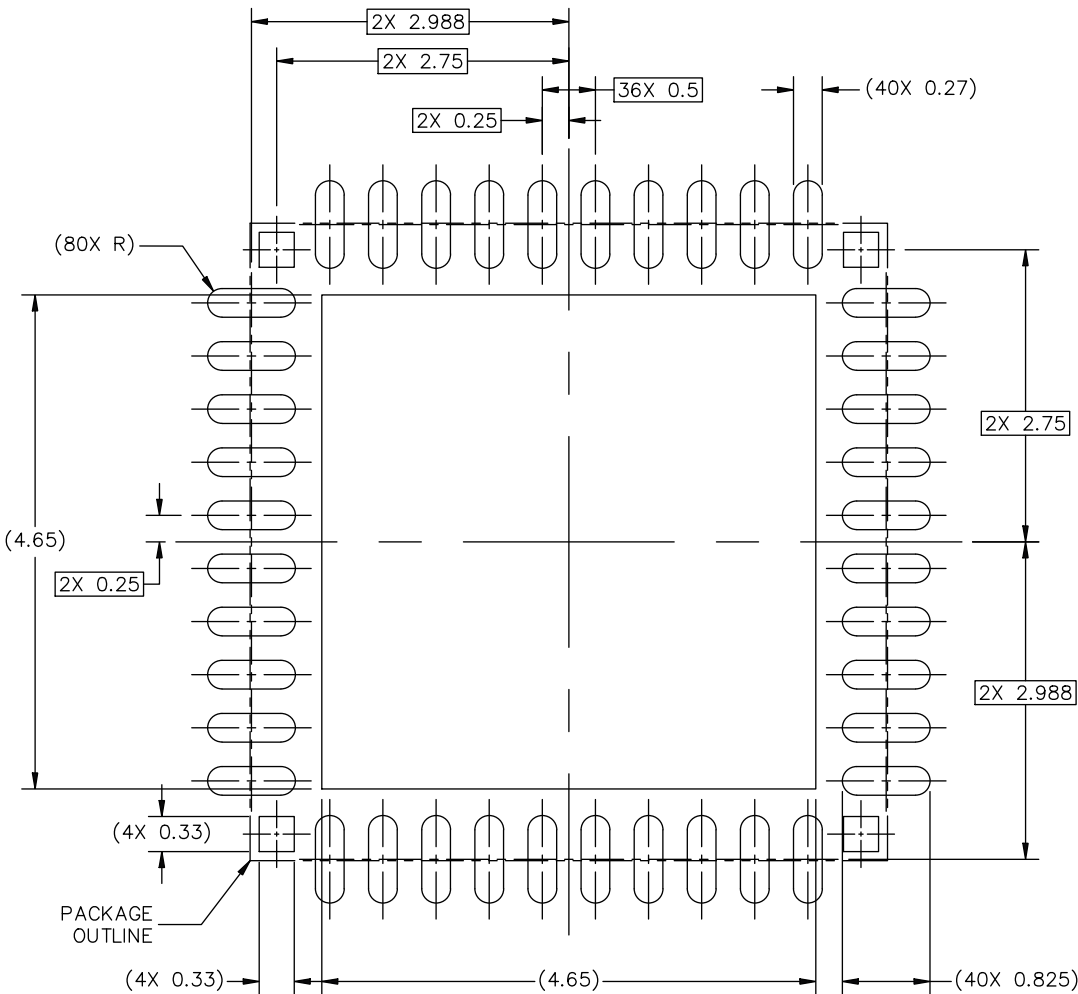


Figure 3. Reflow soldering footprint part1 for HVQFN40 (SOT618-20(D))

HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-20(D)



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

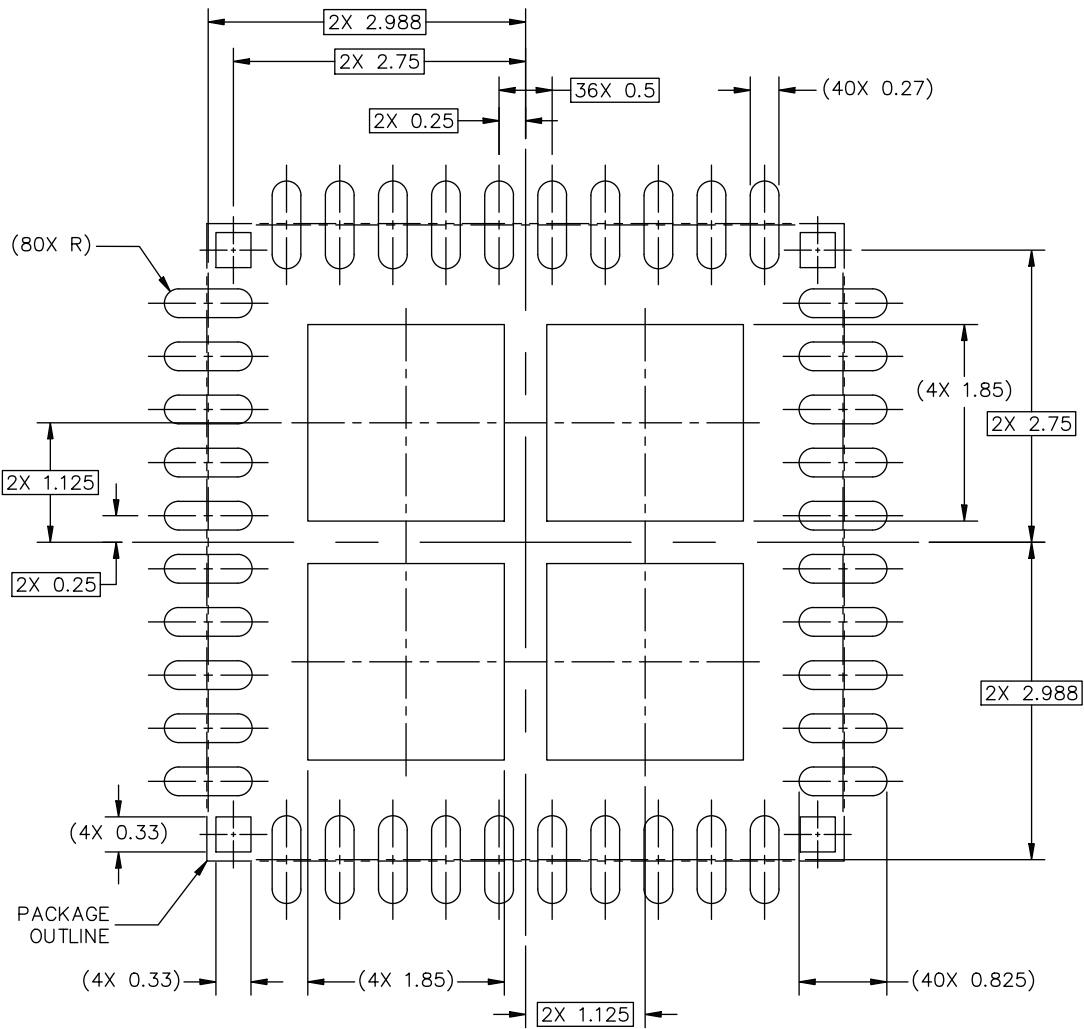
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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01786D	REVISION: 0

Figure 4. Reflow soldering footprint part2 for HVQFN40 (SOT618-20(D))

HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-20(D)



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for HVQFN40 (SOT618-20(D))

HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

H-PQFN-40 I/O 0.1 DIMPLE WETTABLE FLANK
6 X 6 X 0.85 PKG, 0.5 PITCH

SOT618-20(D)

- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS, ANCHORING PADS AND DIE ATTACH FLAG.
 - 5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
 - 6. ANCHORING PADS.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01786D	REVISION: 0

Figure 6. Package outline note HVQFN40 (SOT618-20(D))

HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

4 Legal information

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HVQFN40, thermal enhanced very thin quad flatpack; no leads, 40 terminals, 0.5 mm pitch, 6 mm x 6 mm x 0.85 mm body

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